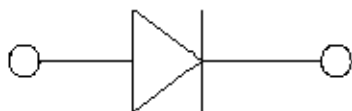


# SD101AWS THRU SD101CWS

## Small Signal Schottky Diode

### Features

- $V_R$  60V/50V/40V
- $I_{FAV}$  70mA



### Mechanical Data

- **Package:** SOD323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

	Marking
SD101AWS	S1
SD101BWS	S2
SD101CWS	S3

### ■Maximum Ratings ( $T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Reverse voltage	$V_R$	V	$I_R=10\mu\text{A}$	SD101AWS	60
				SD101BWS	50
				SD101CWS	40
Average forward current	$I_{FAV}$	mA	$T_c=25^\circ\text{C}$	70	
Power dissipation	$P_D$	mW		200	
Maximum junction temperature	$T_j$	$^\circ\text{C}$		-55 to +125	
Storage temperature range	$T_{stg}$	$^\circ\text{C}$		-55 to +150	
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	$^\circ\text{C}/\text{W}$		500	

### ■Electrical Characteristics ( $T_a=25^\circ\text{C}$ Unless otherwise specified)

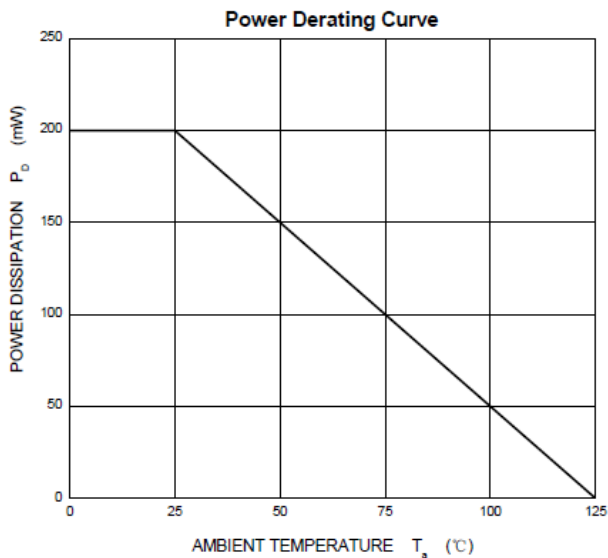
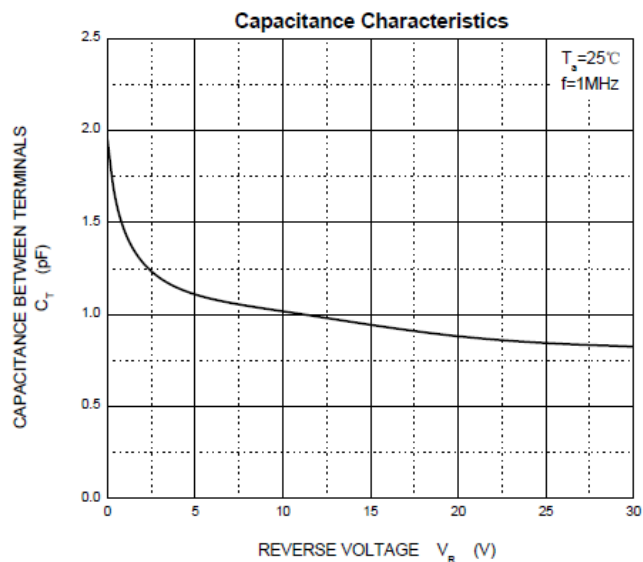
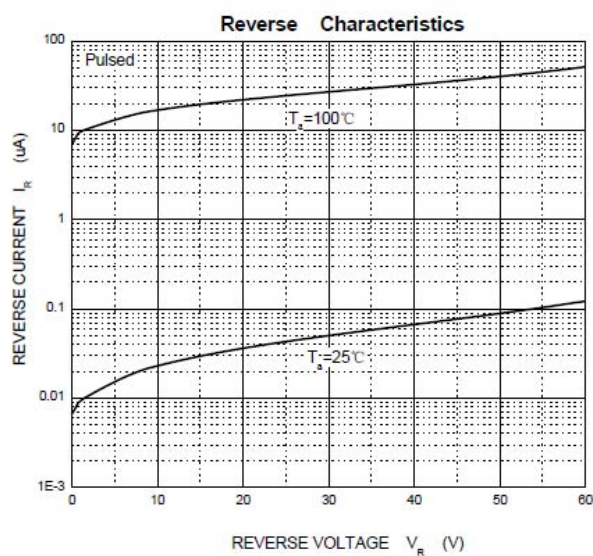
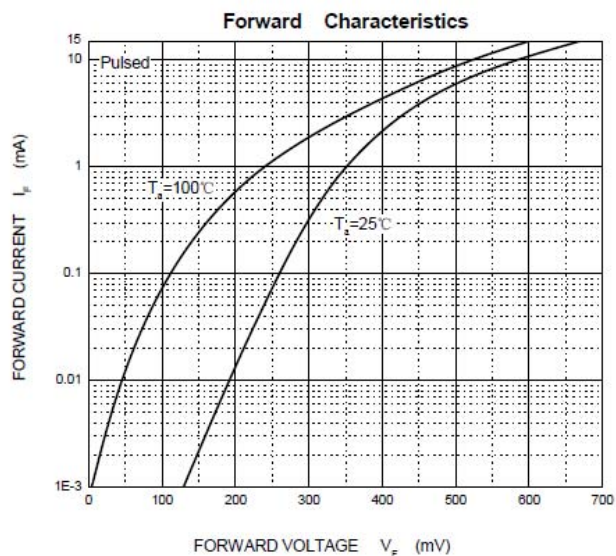
PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Maximum Forward voltage	$V_F$	V	$I_F=1\text{mA}, T_A=25^\circ\text{C}$	SD101AWS	0.41
				SD101BWS	0.4
				SD101CWS	0.39
	$V_F$	V	$I_F=15\text{mA}, T_A=25^\circ\text{C}$	1.0	
Maximum Reverse current	$I_R$	$\mu\text{A}$	SD101AWS	$V_R=50\text{V}, T_A=25^\circ\text{C}$	0.2
			SD101BWS	$V_R=40\text{V}, T_A=25^\circ\text{C}$	
			SD101CWS	$V_R=30\text{V}, T_A=25^\circ\text{C}$	
Minimum Breakdown voltage	$V_{(BR)}$	V	$I_R=10\mu\text{A}$	SD101AWS	60
				SD101BWS	50
				SD101CWS	40
Maximum Junction capacitance	$C_J$	pF	$V_R=1\text{V}, f=1\text{MHz}$	2	

# SD101AWS THRU SD101CWS

## ■ Ordering Information (Example)

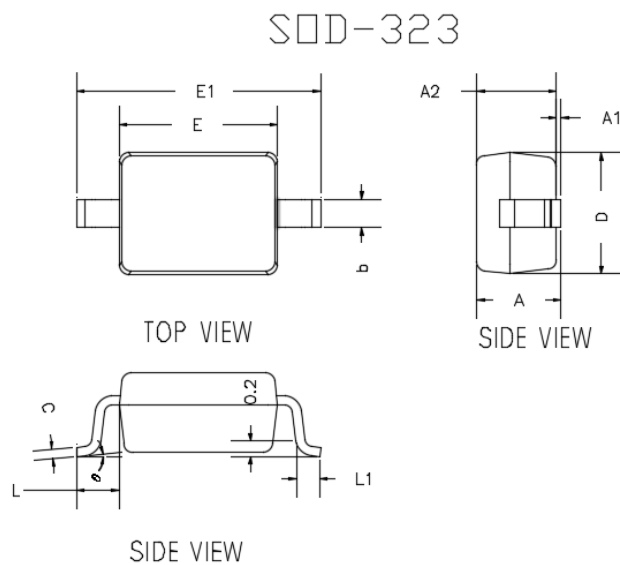
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SD101AWS Thru SD101CWS	F2	Approximate 0.0048	3000	30000	120000	7" reel

## ■ Characteristics (Typical)



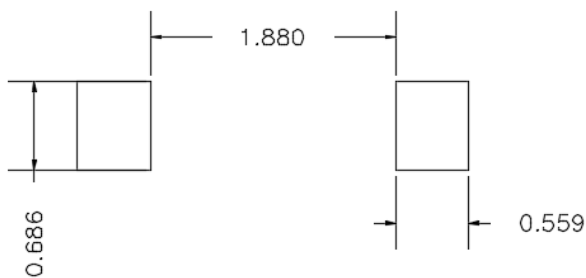
# SD101AWS THRU SD101CWS

## ■ Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
θ	0°	8°	0°	8°

## ■ Soldering Footprint



UNIT : mm

SUGGESTED SOLDER PAD LAYOUT

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